

WLCSP

Wafer Level Processing & Die Processing Services (WLP/DPS)

Amkor Technology offers Wafer Level Chip Scale Packaging (WLCSP), providing a solder interconnection directly between a device and the motherboard of the end product. WLCSP includes wafer bumping (with or without pad layer redistribution or RDL), wafer level final test (probe), device singulation and packing in tape & reel to support a full turnkey solution.

Amkor's robust Under Bump Metallurgy (UBM) over PBO or PI dielectric layers on the die active surface provides a reliable interconnect solution able to survive harsh board level conditions meeting the demands of the growing global consumer market place for portable electronics.

WAFER LEVEL FEATURES

- ▶ 4-196 ball count
- ▶ Small body 0.16 mm² to large 100.0 mm² body size
- ▶ Polyimide (PI), PBO, low-cure polymers and Redistribution Layer (RDL) available
- ▶ Electroplated Sn/Ag <0.3 mm and SAC alloy ball-loaded bumping options ≥0.25 mm pitch
- ▶ Reliable thick Cu UBM or Ni/Au for best in class EM performance
- ▶ Compatible with conventional SMT assembly and test techniques

DIE LEVEL FEATURES

- ▶ Best in class component and board level reliability
- ▶ JEDEC tested board level performance demonstrated without underfill
- ▶ Precision edge quality ensuring device integrity at board mount
- ▶ Back-side laminate coating available
- ▶ Cost effective T&R packaging solutions for small ICs
- ▶ Ultra-thin backgrinding for embedded die applications
- ▶ Full turnkey WLP, contact probe and DPS supported in Taiwan, China, Portugal and Korea
- ▶ Wide selection of pocket tape carrier options

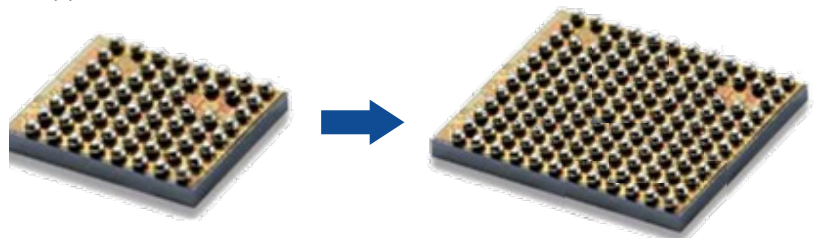
Fueling Growth

- ▶ Small packages in mobile are critical to maximize battery size
- ▶ Level of adoption in fastest growing markets (i.e., tablets and smartphones)
- ▶ Extension of the technology platform to a wider field of application areas is ongoing
- ▶ Dis-integration of high performance functions from processors to new specialized devices (e.g., audio)
- ▶ Fewer cycles through electrical test
- ▶ Lower cost to EMS assembly MSL L1 package from T&R
- ▶ Improved SMT-compatible underfill processes at EMS companies increase prior die size limits

Applications

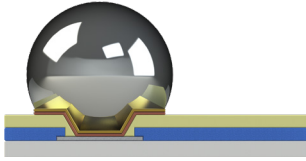
The WLCSP package family is applicable for a wide range of semiconductor device types from high end RF WLAN combo chips, to FPGAs, power management, Flash/EEPROM, integrated passive networks and standard analog. WLCSP offers the lowest total cost of ownership enabling higher semiconductor content while leveraging the smallest form factor and one of the highest performing, most reliable, semiconductor package platforms on the market today.

WLCSP is ideally suited for, but not limited to, mobile phones, tablets, netbook PCs, disk drives, digital still & video cameras, navigation devices, game controllers, other portable/remote products and some automotive end applications.



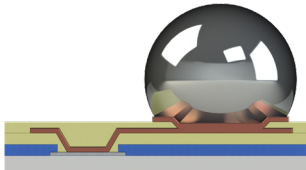
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CSP^{nl} Bump on Repassivation



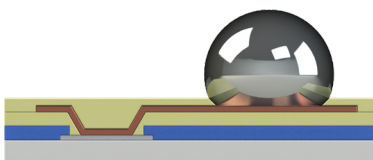
The CSP^{nl} Bump on Repassivation (BoR) option provides a reliable, cost-effective, true chip size package on devices not requiring redistribution. The BoR option utilizes a repassivation polymer layer with excellent electrical/mechanical properties. A UBM is added, and solder bumps are then placed directly over die I/O pads. CSP^{nl} is designed to utilize industry-standard surface mount assembly and reflow techniques.

CSP^{nl} Bump on Redistribution



The CSP^{nl} bump on redistribution option adds a plated copper Redistribution Layer (RDL) to route I/O pads to JEDEC/EIAJ standard pitches, avoiding the need to redesign legacy parts for CSP applications. A nickel-based or thick copper UBM offering, along with polyimide or PBO dielectrics, provide best in class board level reliability performance. CSP^{nl} with RDL utilizes industry-standard surface mount assembly and reflow techniques, and does not require underfill on qualified device size and I/O layouts.

CSPⁿ³



The CSPⁿ³ option utilizes one layer of copper for both redistribution and UBM. This simplified process flow reduces cost and cycle time by over 20%. CSPⁿ³ has been in production since 2009 and has a run rate of over 4 billion units since its introduction.

Package Options

Ball Loading

Pitch	Sphere Diameter
0.50 mm	0.30 mm
0.40 mm	0.25 mm
0.35 mm	0.22 mm
0.30 mm	0.18 mm
0.25 mm	0.13 mm

Reliability Qualification

Package Level

- ▶ Preconditioning at level 1: 85°C/85% RH, 168 hours, (unlimited out of bag life) reflow @ 260°C peak
- ▶ Temp cycle: -55°C/+125°C, 1000 cycles
- ▶ High temp storage: 150°C, 1000 hours

Board Level

- ▶ Temp cycle: -40°C/+125°C, 15 minute ramp rate, ≥500 cycles
- ▶ Drop test: JEDEC condition B (1500G), ≥100 drops

Process Highlights

- ▶ Die thickness: 80 μm* to 450 μm
- ▶ Bump height
 - ▷ 0.5 mm pitch: 250 μm
 - ▷ 0.4 mm pitch: 198 μm
 - ▷ 0.35 mm pitch: 166 μm
 - ▷ 0.3 mm pitch: 130 μm
 - ▷ 0.25 mm pitch: 98 μm
- ▶ Solder ball pitch: 0.25, 0.3, 0.35, 0.4, 0.5 mm (ball loaded)
- ▶ Pitch (plated): 0.08 to 0.25 mm
- ▶ Solder sphere dia: 0.15, 0.18, 0.22, 0.25, 0.3 mm
- ▶ Redistribution trace/space (min)
 - ▷ CSP^{nl}: 10/10 μm
 - ▷ CSPⁿ³: 12/12 μm
- ▶ Via diameter (min)
 - ▷ PBO: 15 μm
 - ▷ Polyimide: 25 μm (lower possible for low temp polymers)
- ▶ Backside laminate: Available (black)
- ▶ Saw street (min): 50 μm (passivation free space)

*Advanced manufacturing rules may be required. Contact Amkor Business Unit for additional information.

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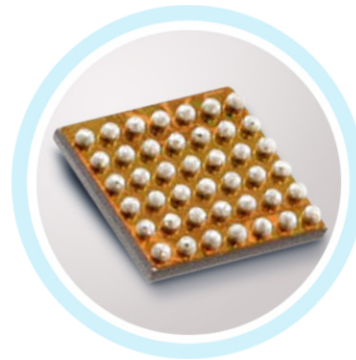
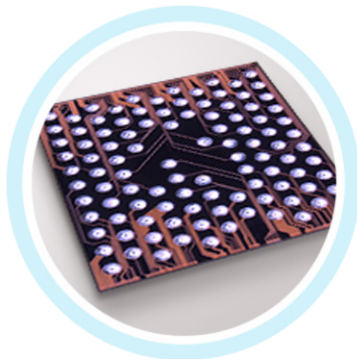
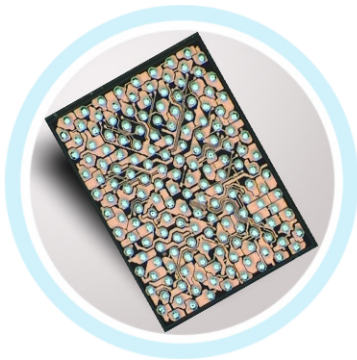
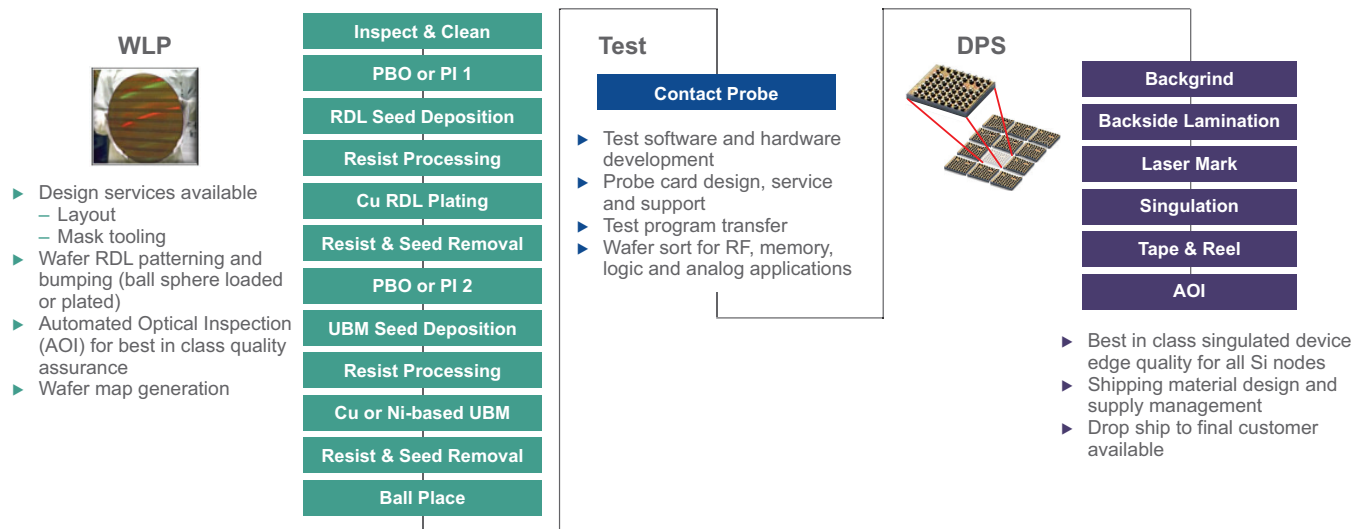
Standard Materials

- ▶ Dielectric materials: Polyimide, PBO, low-cure polymers
- ▶ RDL metalization: Plated copper
- ▶ UBM: Thick Cu or Ni-based
- ▶ Solder composition
 - ▷ (Ball loaded) Pb-free SAC alloys
 - ▷ (Plated) Sn/Ag Pb-free, Cu pillar

Shipping

- ▶ Carrier tape 7", 13" reels

Capabilities and Services



Visit amkor.com or email sales@amkor.com for more information.



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